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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/848,140	05/03/2001	Hideyo Osanai	134.136	7450
759	90 03/02/2005		EXAM	INER
JAMES H. PATTERSON			DINH, TUAN T	
PATTERSON, 7	ΓHUENTE, SKAAR & CΙ	HRISTENSEN, P.A.		
4800 IDS CENT	TER		ART UNIT	PAPER NUMBER
80 SOUTH 8TH	STREET		2841	
MINNEAPOLIS	S, MN 55402-2100		DATE MAILED: 03/02/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	•		H: A
•	Application No.	Applicant(s)	
Office Action Summers	09/848,140	OSANAI ET AL.	
* Office Action Summary	Examiner	Art Unit	
The MAILING DATE of this communication and	Tuan T. Dinh	2841	• 
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address	
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period we Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communicati D (35 U.S.C. & 133).	on.
Status			
Responsive to communication(s) filed on <u>08 December</u> This action is <b>FINAL</b> . 2b) ☐ This      Since this application is in condition for allowed closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro		is
Disposition of Claims		<u>.</u>	
4) ☐ Claim(s) 1-7 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-7 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or			
Application Papers			
9) The specification is objected to by the Examiner 10) The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction of the option	epted or b) objected to by the liderating of the liderating of behind in abeyance. See on is required if the drawing(s) is object.	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121	(d).
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list of	s have been received. s have been received in Application ity documents have been received (PCT Rule 17.2(a)).	on No ed in this National Stage	
Attachment(s)			
<ol> <li>Notice of References Cited (PTO-892)</li> <li>Notice of Draftsperson's Patent Drawing Review (PTO-948)</li> <li>Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 12/04,01/05</li> </ol>	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:		

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#### **DETAILED ACTION**

## Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-2, and 4-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chang (U. S. Patent 4,531,044) in view of Baba et al. (U. S. Patent 4,284,437).

As to claims 1, 4-6, Chang disclose a metal-ceramic circuit board as shown in figures 3 and 8 comprising

a aluminum alloy base plate (16, column 4, line 9) and a ceramic substrate board (15, column 4, line 5) made of alumina (column 4, lines 23-29), wherein one surface (a bottom surface) of the ceramic substrate board (15) is bonded directly to the aluminum base plate (16), see figure 3, the aluminum base plate (16) having a thickness not smaller than 1mm, see column 4, lines 32-34.

Chang does not disclose the aluminum alloy base plate having a proof stress not higher than 320Mpa.

Baba et al. show a aluminum alloy base plate having a proof stress not higher than 320Mpa, see column 4, lines 22-42, column 7, line 8, and also, see tables 2 and 6.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to employ a proof stress (yielding strength) not higher than 320Mpa

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of a aluminum/aluminum alloy base plate in the metal-ceramic circuit board of Chang, as taught by Hayashi et al., in order to provide a maximum deflection and anti breaking strengths of the metal base of the circuit board.

As to claim 2, Chang disclose the board as shown in figures 3 and 8 wherein the other surface (a top surface) of the ceramic substrate board (15) has a metal conductive member (14, column 4, lines 4-5).

As to claim 7, Chang disclose a module (column 1, line 57) as shown in figures 3 and 8 comprising

- a aluminum alloy base plate (16),
- a ceramic substrate board (15), and

a semiconductor tip (14), wherein one surface of the ceramic substrate (15) board is bonded directly to the base plate (16), said semiconductor tip (14) is provided on the other surface of said ceramic substrate board (15), the aluminum base plate (16) having a thickness not smaller than 1mm, see column 4, lines 32-34.

Chang does not disclose the aluminum alloy base plate having a proof stress not higher than 320Mpa.

Baba et al. show a aluminum alloy base plate having a proof stress not higher than 320Mpa, see column 4, lines 22-42, column 7, line 8, and also, see tables 2 and 6.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to employ a proof stress (yielding strength) not higher than 320Mpa of a aluminum/aluminum alloy base plate in the metal-ceramic circuit board of Chang.

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as taught by Hayashi et al., in order to provide a maximum deflection and anti breaking strengths of the metal base of the circuit board.

3. Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over Chang ('044) in view of Baba et al. ('437) as applied to claims 1-2, and 4-7 above, and further in view of Nagase et al. (U. S. Patent 6,033,787).

Chang and Baba disclose all of the limitations of the claimed invention, except for the conductive member is made of a material selected from copper/copper alloy, and aluminum/aluminum alloy.

Nagase et al. shows a metal conductive member (11) made of aluminum material bonded on a ceramic substrate (13), see figure 1.

It would have been obvious to one having ordinary skill in the art at the time the invention was made to employ a metal conductive member made of aluminum on the substrate of Chang in view of Baba, as taught by Nagase et al. for the purpose of improving a thermal conductivity and heat resistance.

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### Response to Arguments

Applicant's arguments filed 12/08/05 have been fully considered but they are not persuasive.

Applicant argues:

(a) Chang is directed to a method of laser soldering electrical lead strands, and Baba is directed to a process for preparing a hard tempered aluminum alloy sheet by hot rolling, and there is no suggestion or motivation for combination.

Examiner disagrees. Examiner gave a motivation for combining in the rejection.

Thus, the combination of Chang in view of Baba would be moet and proper.

RW2 2/25/05

(b) Chang reference does not disclose the ceramic substrate board is bonded directly to the base plate.

Examiner disagrees. It is clearly shown in figure 3 that the Chang reference disclosed the ceramic substrate (15) is directly bonded to the base plate (16), and also, because there is no brazing material formed between the substrate (15) and the base plate (16), and just only glue for directly bonded a surface of the substrate and a surface of the base plate together.

#### Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within

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TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Tùan Dinh February 22, 2005.

> RANDIJW.GIBSON PRIMARY EXAMINER